

TSG30N120B

IGBT

DRAWING

Features

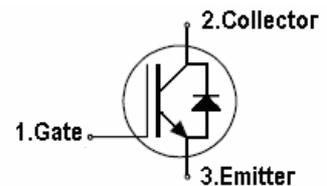
- 1200V,30A
- $V_{CE(sat)(typ.)}=2.1V@V_{GE}=15V$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA



G C E

General Description

TS NPT IGBTs offer lower losses and higher energy efficiency for application such as IH (induction heating), UPS, general inverter and other soft switching applications.



Absolute Maximum Ratings

Symbol	Parameter	Spec	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 30	V
I_C	Continuous Collector Current ($T_C=25\text{ }^\circ\text{C}$)	55	A
	Continuous Collector Current ($T_C=100\text{ }^\circ\text{C}$)	28	A
I_{CM}	Pulsed Collector Current (Note 1)	240	A
I_F	Diode Continuous Forward Current ($T_C=100\text{ }^\circ\text{C}$)	25	A
I_{FM}	Diode Maximum Forward Current (Note 1)	240	A
tsc	Short Circuit Withstand Time	10	us
P_D	Maximum Power Dissipation ($T_C=25\text{ }^\circ\text{C}$)	300	W
	Maximum Power Dissipation ($T_C=100\text{ }^\circ\text{C}$)	120	W
T_J	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	Spec	Units
Rth j-c	Thermal Resistance, Junction to case for IGBT	0.42	$^\circ\text{C}/\text{W}$
Rth j-c	Thermal Resistance, Junction to case for Diode	0.83	$^\circ\text{C}/\text{W}$
Rth j-a	Thermal Resistance, Junction to Ambient	40	$^\circ\text{C}/\text{W}$

Electrical Characteristics (TC=25℃ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units	
BV_{CES}	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	1200			V	
I_{CES}	Collector-Emitter Leakage Current	$V_{CE}=1200V, V_{GE}=0V$			250	μA	
I_{GES}	Gate Leakage Current, Forward	$V_{GE}=30V, V_{CE}=0V$			100	nA	
	Gate Leakage Current, Reverse	$V_{GE}=-30V, V_{CE}=0V$			-100	nA	
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	4	5	6	V	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=30A$		2.1	2.3	V	
Q_g	Total Gate Charge	$V_{CC}=960V$		178		nC	
Q_{ge}	Gate-Emitter Charge	$V_{GE}=15V$		36		nC	
Q_{gc}	Gate-Collector Charge	$I_C=30A$		84		nC	
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V$ $V_{GE}=0V/15V, I_C=30A$ $R_G=28\Omega$ Inductive Load TC=25℃		54		ns	
t_r	Turn-on Rise Time			72		ns	
$t_{d(off)}$	Turn-off Delay Time			671		ns	
t_f	Turn-off Fall Time			44		ns	
E_{on}	Turn-on Switching Loss			2.9		mJ	
E_{off}	Turn-off Switching Loss			2.2		mJ	
E_{ts}	Total Switching Loss			5.1		mJ	
C_{ies}	Input Capacitance		$V_{CE}=30V$		645		pF
C_{oes}	Output Capacitance		$V_{GE}=0V$		206		pF
C_{res}	Reverse Transfer Capacitance		$f=100kHz$		115		pF
R_{Gint}	Integrated gate resistor			2.1		Ω	

Electrical Characteristics of Diode (TC=25℃ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
V_F	Diode Forward Voltage	$I_F=30A$		2.0	2.2	V
t_{rr}	Diode Reverse Recovery Time	$V_{CE}=600V$ $I_F=30A$ $dI_F/dt=200A/\mu s$		197		ns
I_{rr}	Diode peak Reverse Recovery Current			20		A
Q_{rr}	Diode Reverse Recovery Charge				1923	

Typical Characteristics

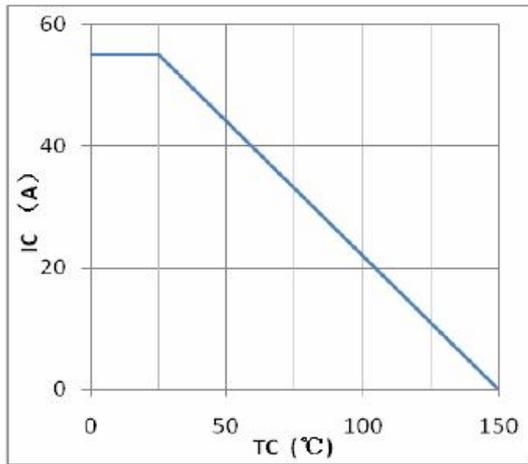


Figure1: maximum DC collector current VS. case temperature

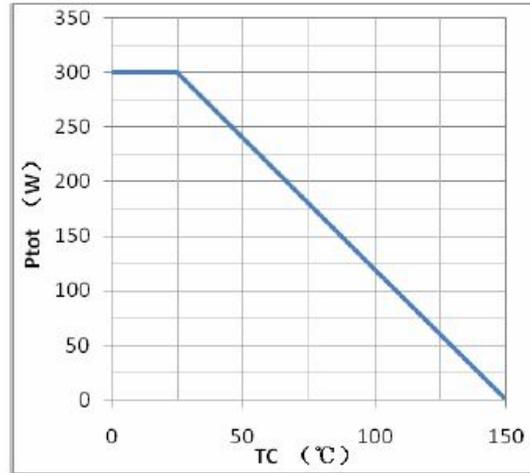


Figure2: power dissipation VS. case temperature

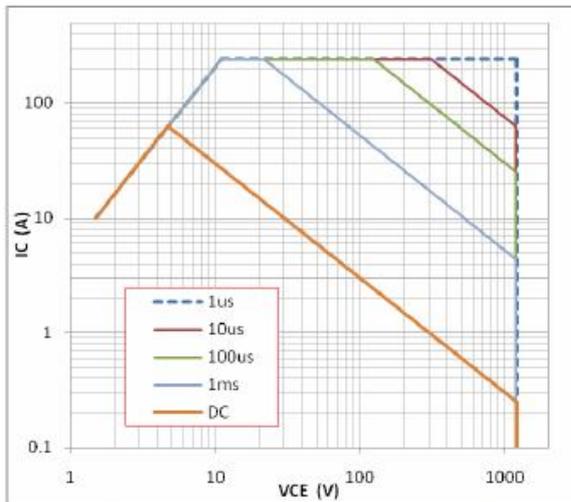


Figure3: forward SOA, TC=25°C, TJ ≤ 150°C

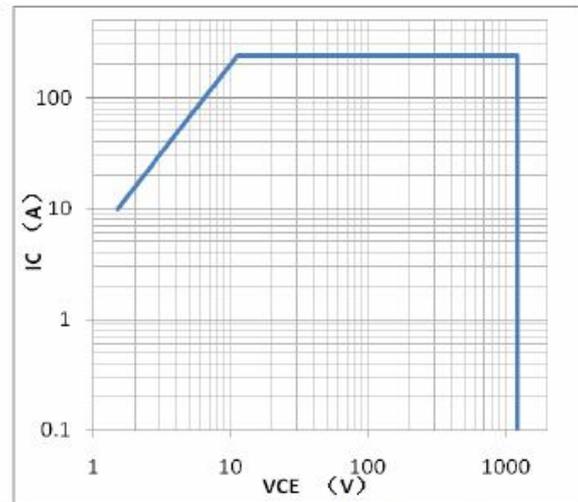


Figure4: reverse bias SOA, TJ=150°C, VGE=15V

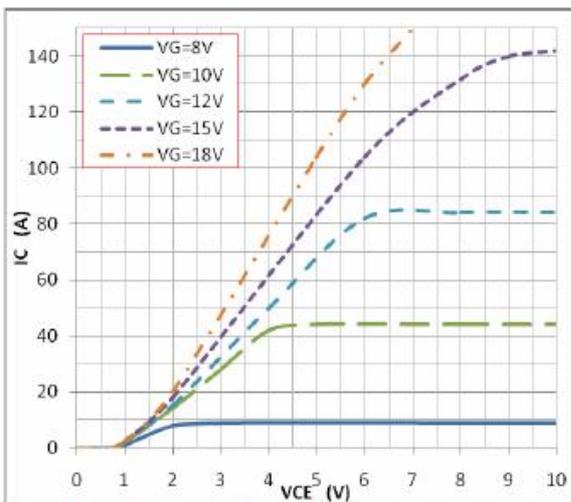


Figure5: typical IGBT output characteristics, TJ=25°C, tp=300us

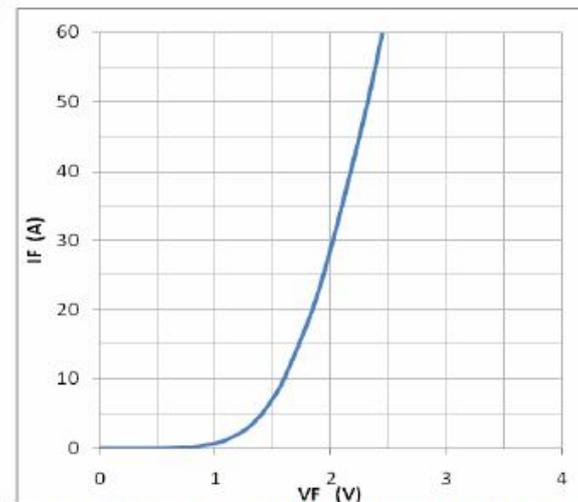


Figure6: typical trans characteristics, VCE=20V, tp=20us

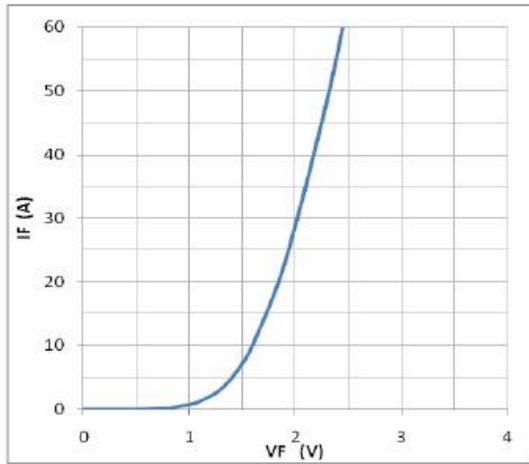


Figure7: typical diode forward characteristic, $t_p=300\mu s$

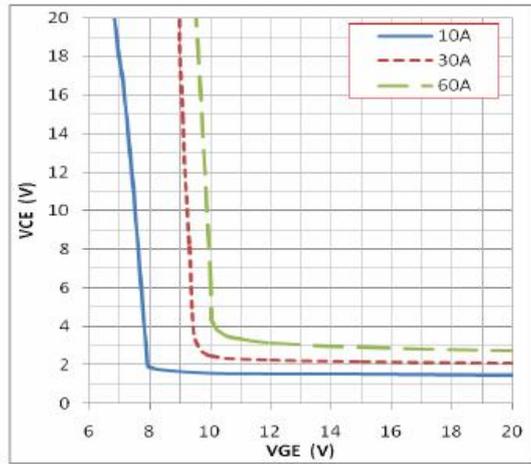


Figure8: typical V_{CE} VS. V_{GE} , $T_J=25^\circ C$

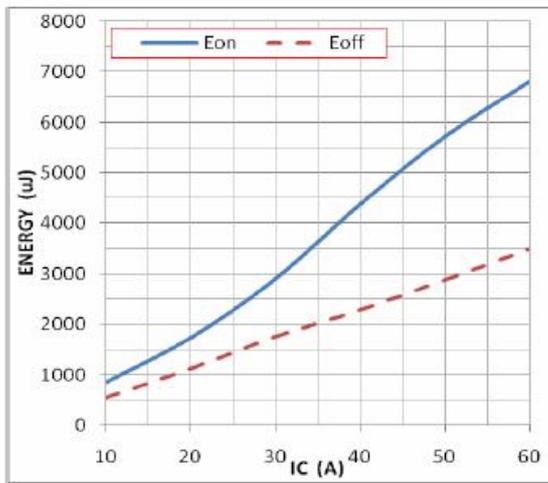


Figure 9: typical energy loss VS. I_C , $T_C=25^\circ C$, $L=500\mu H$,
 $V_{CE}=600V$, $V_{GE}=15V$, $R_g=28\Omega$

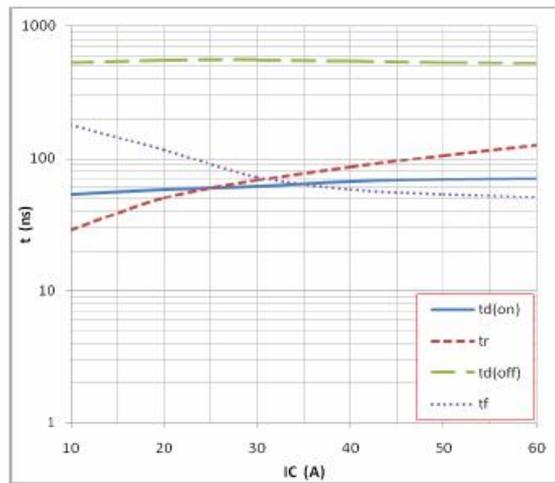


Figure10: typical switching time VS. I_C , $T_C=25^\circ C$,
 $L=500\mu H$, $V_{CE}=600V$, $V_{GE}=15V$, $R_g=28\Omega$

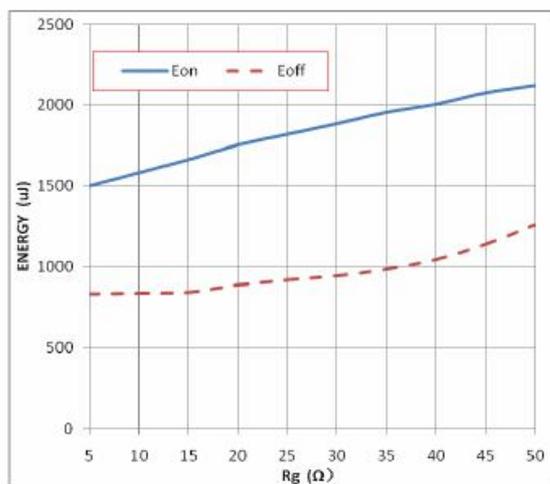


Figure11: typical energy loss VS. R_g , $T_C=25^\circ C$,
 $L=500\mu H$, $V_{CE}=600V$, $V_{GE}=15V$, $I_C=30A$

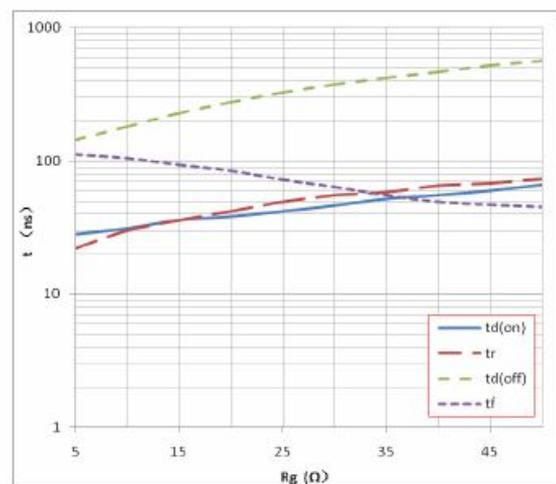


Figure12: typical switching time VS. R_g , $T_C=25^\circ C$,
 $L=500\mu H$, $V_{CE}=600V$, $V_{GE}=15V$, $I_C=30A$

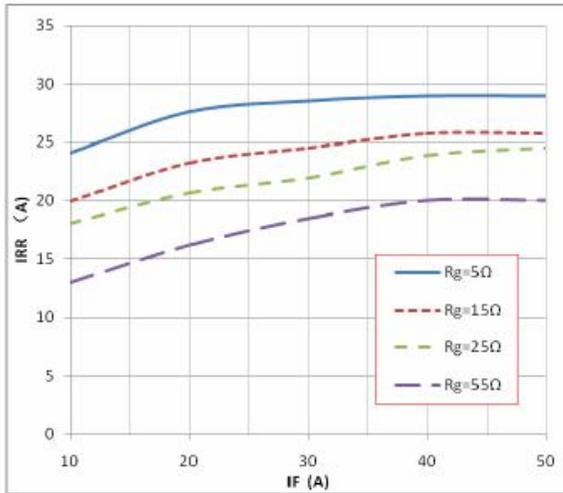


Figure13: typical diode IRR VS. IF, TC=25°C

VCC=600V,VGE=15V

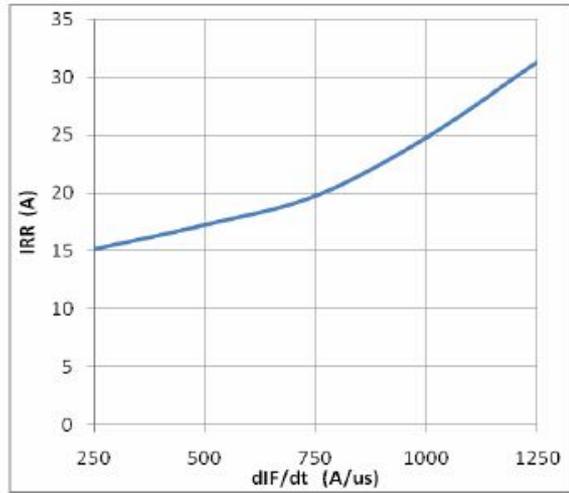


Figure14: typical diode IRR VS. dIF/dt

VCC=600V,VGE=15V,IF=30A

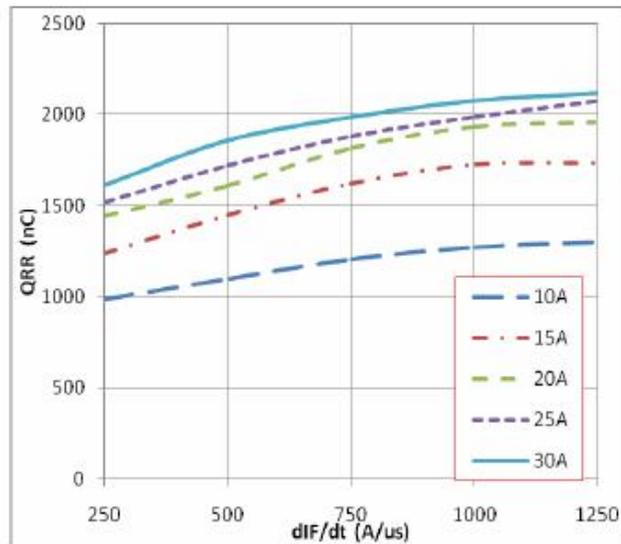


Figure15: typical diode QRR VS. dIF/dt, VCC=600V, VGE=15V

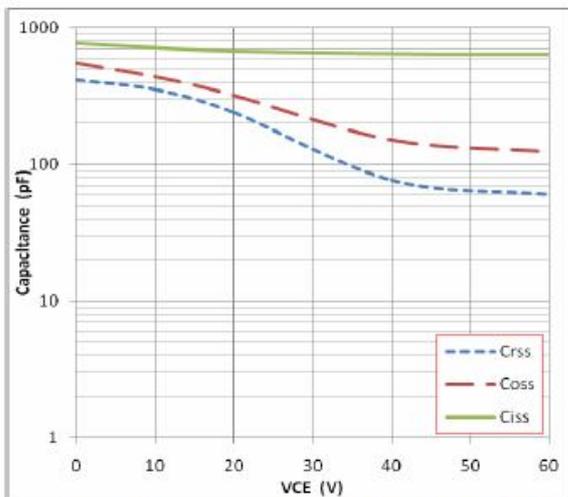


Figure16: typical capacitance VS. VCE, VGE=0V, f=100kHz

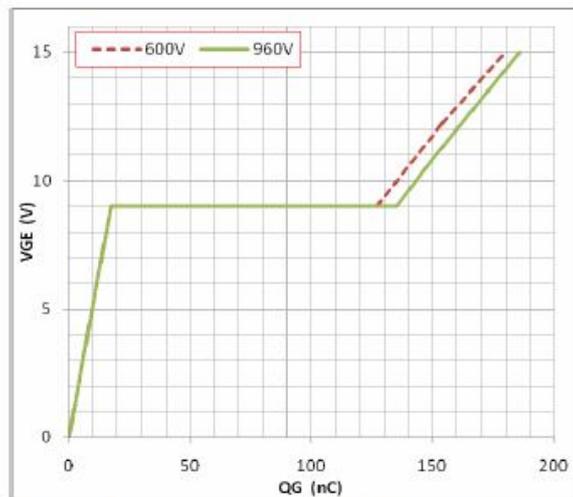


Figure17: typical gate charge VS. VGE, IC=30A

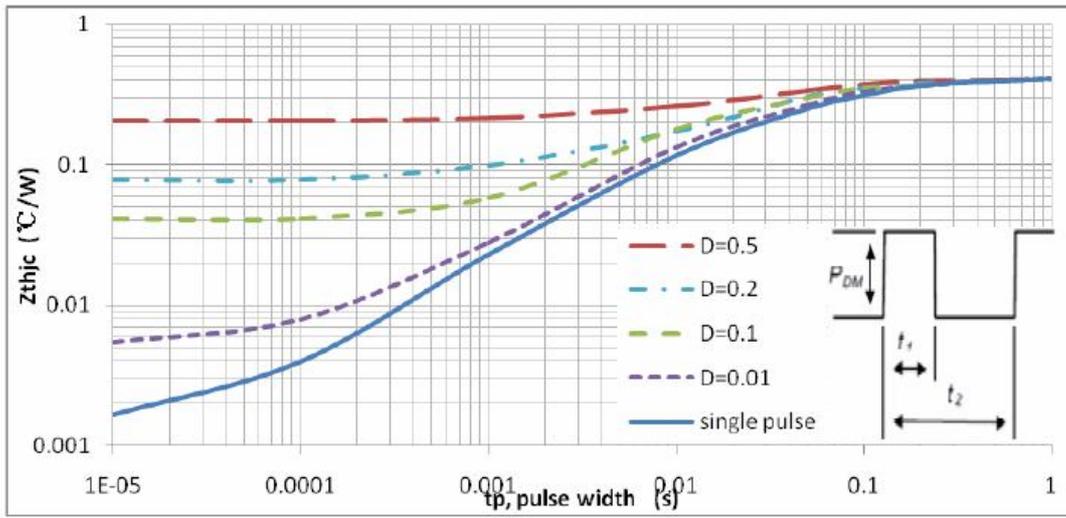


Figure18:normalized transient thermal impedance,junction-to-case
 Note1.Duty factor $D=t_1/t_2$; Note2:peak $T_J=P_{DM} \times Z_{thjc}+T_C$

Mechanical Dimensions

